



SOT470-4

HLQFP100, plastic, thermal enhanced low profile quad flat package; 100 terminals; 0.5 mm pitch; 14 mm x 14 mm x 1.4 mm body

16 January 2019

Package information

1 Package summary

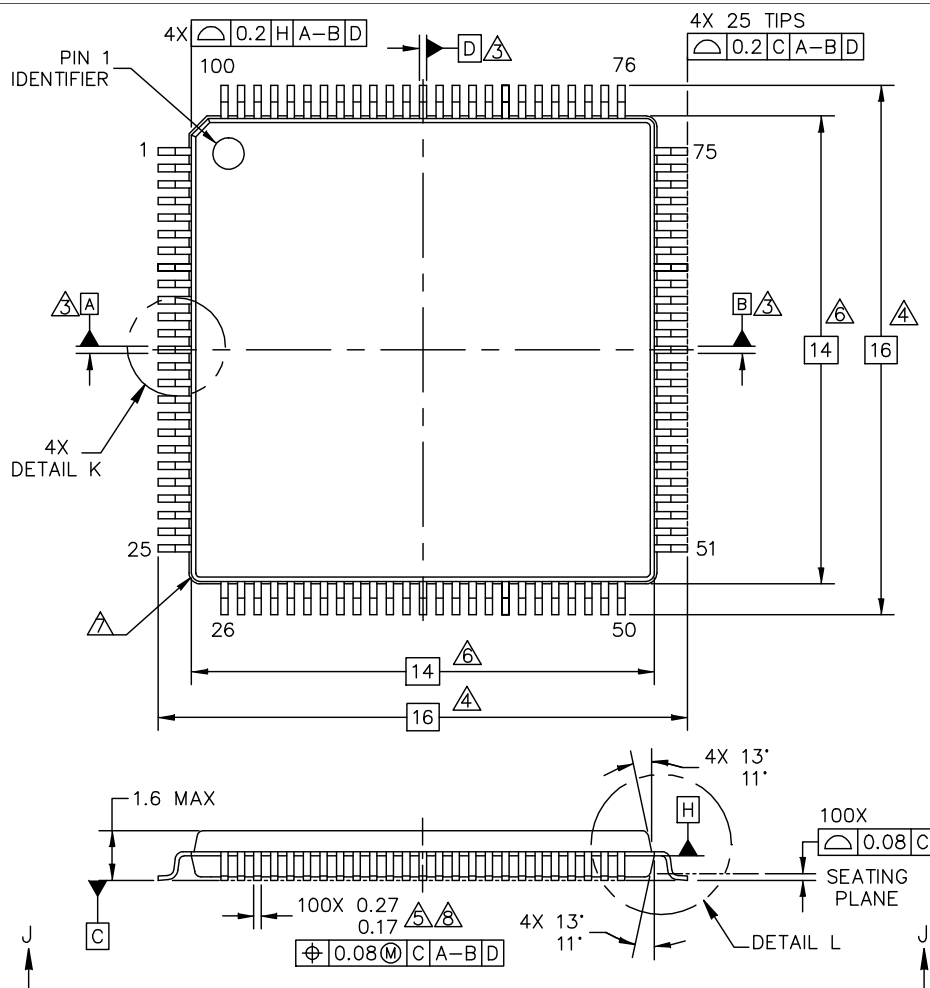
Terminal position code	Q (quad)
Package type descriptive code	HLQFP100
Package style descriptive code	HLQFP (thermal enhanced low profile quad flat package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	18-03-2016
Manufacturer package code	98ASA00293D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	14	-	mm
package width	-	14	-	mm
package height	-	1.4	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	100	-	



2 Package outline



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TITLE: LQFP, 14 X 14 X 1.4 PKG, 0.5 PITCH, 100 I/O, 6.5 X 6.5 EXPOSED PAD	DOCUMENT NO: 98ASA00293D	REV: D
	STANDARD: NON-JEDEC	
	SOT470-4	18 MAR 2016

Figure 1. Package outline HQFP100 (SOT470-4)

HLQFP100, plastic, thermal enhanced low profile quad flat package; 100 terminals; 0.5 mm pitch; 14 mm x 14 mm x 1.4 mm body

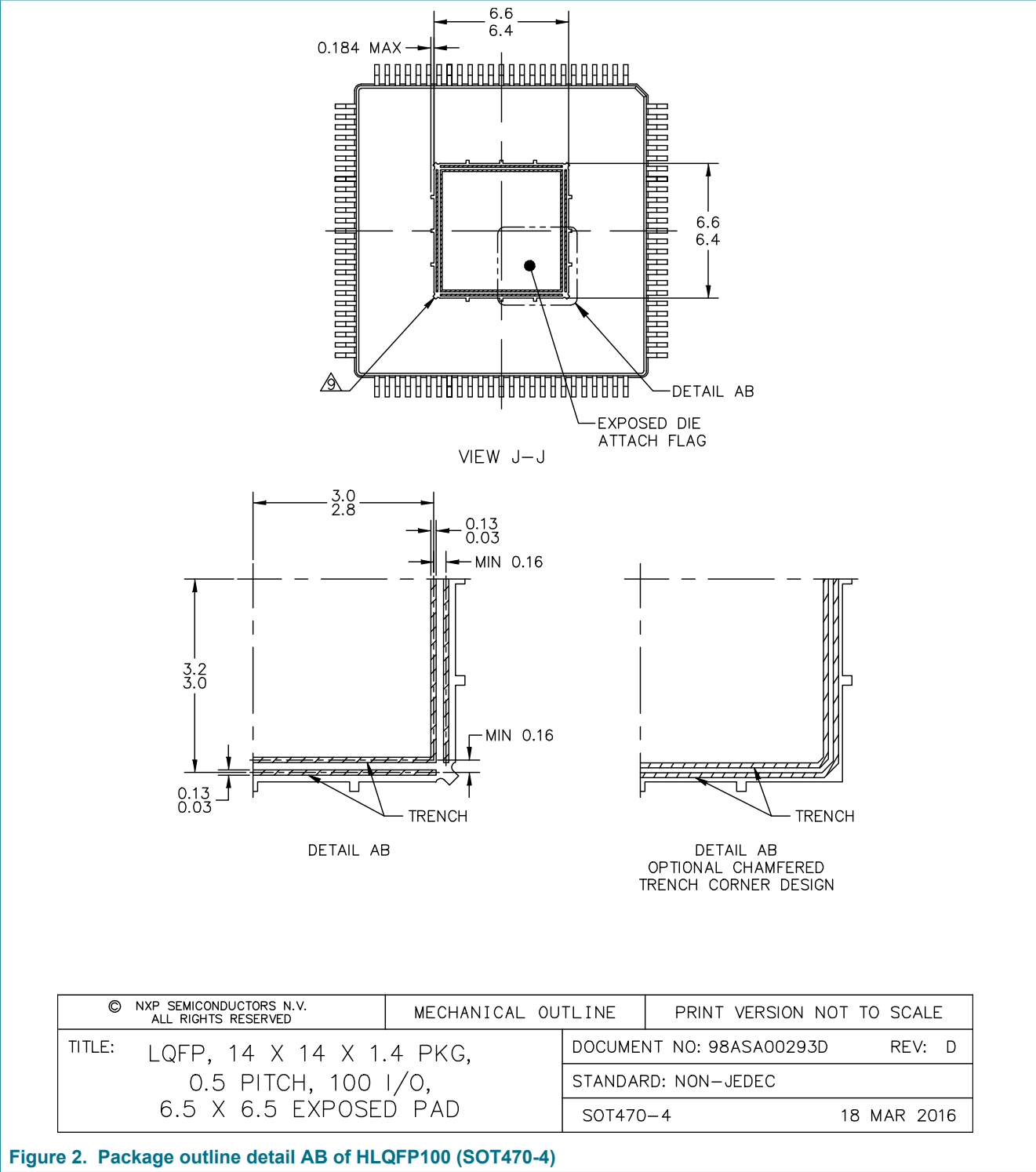


Figure 2. Package outline detail AB of HLQFP100 (SOT470-4)

HLQFP100, plastic, thermal enhanced low profile quad flat package; 100 terminals; 0.5 mm pitch; 14 mm x 14 mm x 1.4 mm body

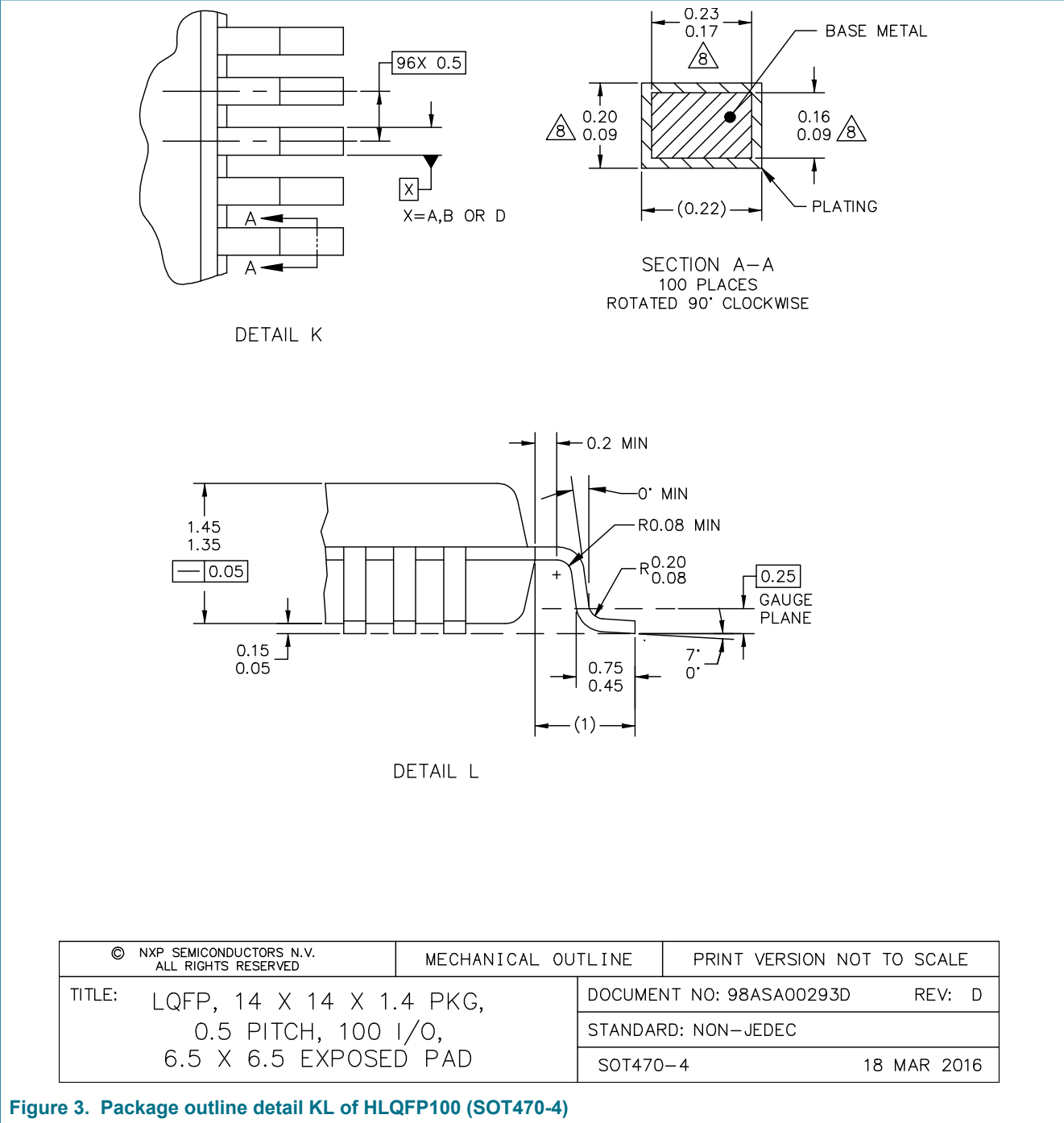


Figure 3. Package outline detail KL of HLQFP100 (SOT470-4)

3 Legal information

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